

L Number	Hits	Search Text	DB	Time stamp
2	1207	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and (solidif\$4 or dispers\$3)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 14:51
3	1416	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria ) and (aluminum or al or titanium or ti or copper or Cu)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:21
4	4113	pad with abrasive	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:22
5	920	((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria ) and (aluminum or al or titanium or ti or copper or Cu) ) and (pad with abrasive)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 14:56
6	76	((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria ) and (aluminum or al or titanium or ti or copper or Cu) ) and (pad with abrasive)) and organic and oxidizer	USPAT; EPO; JPO; IBM_TDB	2003/02/19 14:57
7	80	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria ) and (aluminum or al or titanium or ti or copper or Cu) and (benzotriazole or BTA)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 15:52
8	771	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) same abrasive and pad and slurry and (alumina or silica or ceria ) same (aluminum or al or titanium or ti or copper or Cu)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:18
9	516	((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) same abrasive and pad and slurry and (alumina or silica or ceria ) same (aluminum or al or titanium or ti or copper or Cu) ) and semiconductor	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:17
10	110	(CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) same abrasive same pad same slurry same (alumina or silica or ceria ) same (aluminum or al or titanium or ti or copper or Cu)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:20
11	1733	((438/690) or (438/691) or (438/692) or (438/693)).CCLS.	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:20
12	407	((438/690) or (438/691) or (438/692) or (438/693)).CCLS.) and ((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria ) and (aluminum or al or titanium or ti or copper or Cu) )	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:21
13	1071	pad same attach\$ same abrasive	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:22

14	44	(((438/690) or (438/691) or (438/692) or (438/693)).CCLS.) and ((CMP or "chemical mechanical polishing" or polishing or planarizing or planarization) and abrasive and pad and slurry and (alumina or silica or ceria ) and (aluminum or al or titanium or ti or copper or Cu) ) ) and (pad same attach\$ same abrasive)	USPAT; EPO; JPO; IBM_TDB	2003/02/19 16:22
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